SEMICONDUCTOR PROCESS DEVICE AND WAFER SUPPORT STRUCTURE THEREOF

ABSTRACT

The present disclosure provides a semiconductor process device and a wafer support structure. The wafer support structure includes: a lifting component, a supporting component, a compressing component, and an adjusting component. The lifting component includes a lifting shaft. A mounting section is provided on the top surface of the lifting shaft. A first end of the supporting component is sleeved in a mounting hole of the mounting section. An inner peripheral wall of the mounting hole and an outer peripheral wall of the mounting section are separated by an adjustment space. The compressing component is sleeved on an outer periphery of the mounting section and located in the adjustment space. The adjusting component is connected with the support component. A portion of the adjusting component is located in the adjustment space and squeezes the compressing component to deform to lock the mounting section and the supporting component. The adjusting component is configured to adjust a degree of compression of the compressing component at different positions in a circumferential direction of the mounting hole to adjust levelness and/or a centerline angle of the supporting component. The present disclosure can quickly perform levelness adjustment of the supporting component, thereby reducing cost of assembly and maintenance.

Fig. 1A